

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field Device Integration (FDI) –
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI) –
Partie 101-2: Profils – Foundation Fieldbus HSE**



THIS PUBLICATION IS COPYRIGHT PROTECTED

Copyright © 2015 IEC, Geneva, Switzerland

All rights reserved. Unless otherwise specified, no part of this publication may be reproduced or utilized in any form or by any means, electronic or mechanical, including photocopying and microfilm, without permission in writing from either IEC or IEC's member National Committee in the country of the requester. If you have any questions about IEC copyright or have an enquiry about obtaining additional rights to this publication, please contact the address below or your local IEC member National Committee for further information.

Droits de reproduction réservés. Sauf indication contraire, aucune partie de cette publication ne peut être reproduite ni utilisée sous quelque forme que ce soit et par aucun procédé, électronique ou mécanique, y compris la photocopie et les microfilms, sans l'accord écrit de l'IEC ou du Comité national de l'IEC du pays du demandeur. Si vous avez des questions sur le copyright de l'IEC ou si vous désirez obtenir des droits supplémentaires sur cette publication, utilisez les coordonnées ci-après ou contactez le Comité national de l'IEC de votre pays de résidence.

IEC Central Office
3, rue de Varembe
CH-1211 Geneva 20
Switzerland

Tel.: +41 22 919 02 11
Fax: +41 22 919 03 00
info@iec.ch
www.iec.ch

About the IEC

The International Electrotechnical Commission (IEC) is the leading global organization that prepares and publishes International Standards for all electrical, electronic and related technologies.

About IEC publications

The technical content of IEC publications is kept under constant review by the IEC. Please make sure that you have the latest edition, a corrigenda or an amendment might have been published.

IEC Catalogue - webstore.iec.ch/catalogue

The stand-alone application for consulting the entire bibliographical information on IEC International Standards, Technical Specifications, Technical Reports and other documents. Available for PC, Mac OS, Android Tablets and iPad.

IEC publications search - www.iec.ch/searchpub

The advanced search enables to find IEC publications by a variety of criteria (reference number, text, technical committee,...). It also gives information on projects, replaced and withdrawn publications.

IEC Just Published - webstore.iec.ch/justpublished

Stay up to date on all new IEC publications. Just Published details all new publications released. Available online and also once a month by email.

Electropedia - www.electropedia.org

The world's leading online dictionary of electronic and electrical terms containing more than 30 000 terms and definitions in English and French, with equivalent terms in 15 additional languages. Also known as the International Electrotechnical Vocabulary (IEV) online.

IEC Glossary - std.iec.ch/glossary

More than 60 000 electrotechnical terminology entries in English and French extracted from the Terms and Definitions clause of IEC publications issued since 2002. Some entries have been collected from earlier publications of IEC TC 37, 77, 86 and CISPR.

IEC Customer Service Centre - webstore.iec.ch/csc

If you wish to give us your feedback on this publication or need further assistance, please contact the Customer Service Centre: csc@iec.ch.

A propos de l'IEC

La Commission Electrotechnique Internationale (IEC) est la première organisation mondiale qui élabore et publie des Normes internationales pour tout ce qui a trait à l'électricité, à l'électronique et aux technologies apparentées.

A propos des publications IEC

Le contenu technique des publications IEC est constamment revu. Veuillez vous assurer que vous possédez l'édition la plus récente, un corrigendum ou amendement peut avoir été publié.

Catalogue IEC - webstore.iec.ch/catalogue

Application autonome pour consulter tous les renseignements bibliographiques sur les Normes internationales, Spécifications techniques, Rapports techniques et autres documents de l'IEC. Disponible pour PC, Mac OS, tablettes Android et iPad.

Recherche de publications IEC - www.iec.ch/searchpub

La recherche avancée permet de trouver des publications IEC en utilisant différents critères (numéro de référence, texte, comité d'études,...). Elle donne aussi des informations sur les projets et les publications remplacées ou retirées.

IEC Just Published - webstore.iec.ch/justpublished

Restez informé sur les nouvelles publications IEC. Just Published détaille les nouvelles publications parues. Disponible en ligne et aussi une fois par mois par email.

Electropedia - www.electropedia.org

Le premier dictionnaire en ligne de termes électroniques et électriques. Il contient plus de 30 000 termes et définitions en anglais et en français, ainsi que les termes équivalents dans 15 langues additionnelles. Egalement appelé Vocabulaire Electrotechnique International (IEV) en ligne.

Glossaire IEC - std.iec.ch/glossary

Plus de 60 000 entrées terminologiques électrotechniques, en anglais et en français, extraites des articles Termes et Définitions des publications IEC parues depuis 2002. Plus certaines entrées antérieures extraites des publications des CE 37, 77, 86 et CISPR de l'IEC.

Service Clients - webstore.iec.ch/csc

Si vous désirez nous donner des commentaires sur cette publication ou si vous avez des questions contactez-nous: csc@iec.ch.

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Field Device Integration (FDI) –
Part 101-2: Profiles – Foundation Fieldbus HSE**

**Intégration des appareils de terrain (FDI) –
Partie 101-2: Profils – Foundation Fieldbus HSE**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

COMMISSION
ELECTROTECHNIQUE
INTERNATIONALE

ICS 25.040.40; 35.100

ISBN 978-2-8322-2633-9

**Warning! Make sure that you obtained this publication from an authorized distributor.
Attention! Veuillez vous assurer que vous avez obtenu cette publication via un distributeur agréé.**

CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	7
2 Normative references	7
3 Terms, definitions, abbreviated terms and acronyms	8
3.1 Terms and definitions.....	8
3.2 Abbreviated terms and acronyms	8
4 Conventions	8
4.1 EDDL syntax.....	8
4.2 XML syntax.....	8
5 Profile for CP 1/2 (FOUNDATION™ HSE)	8
5.1 General.....	8
5.2 Catalog profile	8
5.2.1 Protocol support files.....	8
5.2.2 CommunicationProfile definition.....	9
5.2.3 Profile device.....	9
5.2.4 Protocol version information	9
5.3 Associating a Package with a CP 1/2 device	9
5.3.1 Device type identification mapping.....	9
5.3.2 Device type revision mapping	10
5.4 Information Model mapping	10
5.4.1 ProtocolType definition	10
5.4.2 DeviceType mapping	10
5.4.3 FunctionalGroup Identification definition.....	10
5.4.4 BlockType property mapping	11
5.4.5 Mapping to Block ParameterSet.....	11
5.5 Topology elements.....	11
5.5.1 ConnectionPoint definition	11
5.5.2 Communication Device definition	13
5.5.3 Communication service provider definition.....	14
5.5.4 Network definition	15
5.6 Methods.....	15
5.6.1 Methods for FDI Communication Servers	15
5.6.2 Methods for Gateways	22
Annex A (normative) Topology scan schema.....	23
A.1 General.....	23
A.2 Network	23
A.3 FoundationHSEAddressT	23
A.4 FoundationHSEConnectionPointT	23
A.5 FoundationHSENetworkT	24
A.6 FoundationBlockIdentificationT	24
A.7 FoundationIdentificationT	25
Annex B (normative) Transfer service parameters.....	27
Annex C (informative) Communication service arguments for Transfer Method	28
Bibliography.....	29

Table 1 – Capability File part	9
Table 2 – CommunicationProfile definition	9
Table 3 – Device type catalog mapping	9
Table 4 – ProtocolType Foundation_HSE definition	10
Table 5 – Inherited DeviceType property mapping	10
Table 6 – Identification parameters	11
Table 7 – Inherited BlockType property mapping	11
Table 8 – ConnectionPointType ConnectionPoint_Foundation_HSE definition	12
Table 9 – Communication device ParameterSet definition	14
Table 10 – Method Connect arguments	16
Table 11 – Method Disconnect arguments	17
Table 12 – Method Transfer arguments	18
Table 13 – Method GetPublishedData arguments	20
Table 14 – Method SetAddress arguments	21
Table A.1 – Attributes of FoundationHSEConnectionPointT	24
Table A.2 – Elements of FoundationHSEConnectionPointT	24
Table A.3 – Elements of FoundationHSENetworkT	24
Table A.4 – Attributes of FoundationBlockIdentificationT	25
Table A.5 – Attributes of FoundationIdentificationT	26

Document is a preview generated by EVS

INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI) –

Part 101-2: Profiles – Foundation Fieldbus HSE

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested IEC National Committees.
- 3) IEC Publications have the form of recommendations for international use and are accepted by IEC National Committees in that sense. While all reasonable efforts are made to ensure that the technical content of IEC Publications is accurate, IEC cannot be held responsible for the way in which they are used or for any misinterpretation by any end user.
- 4) In order to promote international uniformity, IEC National Committees undertake to apply IEC Publications transparently to the maximum extent possible in their national and regional publications. Any divergence between any IEC Publication and the corresponding national or regional publication shall be clearly indicated in the latter.
- 5) IEC itself does not provide any attestation of conformity. Independent certification bodies provide conformity assessment services and, in some areas, access to IEC marks of conformity. IEC is not responsible for any services carried out by independent certification bodies.
- 6) All users should ensure that they have the latest edition of this publication.
- 7) No liability shall attach to IEC or its directors, employees, servants or agents including individual experts and members of its technical committees and IEC National Committees for any personal injury, property damage or other damage of any nature whatsoever, whether direct or indirect, or for costs (including legal fees) and expenses arising out of the publication, use of, or reliance upon, this IEC Publication or any other IEC Publications.
- 8) Attention is drawn to the Normative references cited in this publication. Use of the referenced publications is indispensable for the correct application of this publication.

International Standard IEC 62769-101-2 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation.

The text of this standard is based on the following documents:

CDV	Report on voting
65E/353/CDV	65E/416/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning

- a) Method for the Supplying and Installation of Device-Specific Functionalities, see Patent Family DE10357276;
- b) Method and device for accessing a functional module of automation system, see Patent Family EP2182418;
- c) Methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186 ;
- d) Extensible Device Object Model, see Patent Family US12/893,680.

IEC takes no position concerning the evidence, validity and scope of this patent right.

The holders of these patent rights have assured the IEC that he/she is willing to negotiate licences either free of charge or under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of the holder of this patent right is registered with IEC. Information may be obtained from:

- a) ABB Research Ltd
Claes Ryttoft
Affolterstrasse 4
Zurich, 8050
Switzerland
- b) Phoenix Contact GmbH & Co KG
Intellectual Property, Licenses & Standards
Flachsmarktstrasse 8, 32825 Blomberg
Germany
- c) Fisher Controls International LLC
John Dilger, Emerson Process Management LLP
301 S. 1st Avenue, Marshalltown, Iowa 50158
USA
- d) Rockwell Automation Technologies, Inc.
1 Allen-Bradley Drive
Mayfield Heights, Ohio 44124
USA

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights other than those identified above. IEC shall not be held responsible for identifying any or all such patent rights.

ISO (www.iso.org/patents) and IEC (<http://patents.iec.ch>) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the data bases for the most up to date information concerning patents.

FIELD DEVICE INTEGRATION (FDI) –

Part 101-2: Profiles – Foundation Fieldbus HSE

1 Scope

This part of IEC 62769 specifies the IEC 62769 profile for IEC 61784-1, CP 1/2 (FOUNDATION™ Fieldbus HSE)¹.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks - Profiles - Part 1: Fieldbus profiles*

IEC 61784-2, *Industrial communication networks - Profiles - Part 2: Additional fieldbus profiles for real-time networks based on ISO/IEC 8802-3*

IEC 61804 (all parts), *Function blocks (FB) for process control*

IEC 62541-100:2015, *OPC Unified Architecture – Part 100: Device interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE IEC 62769-2 is technically identical to FDI-2022.

IEC 62769-3, *Field Device Integration (FDI) – Part 3: FDI Server*

NOTE IEC 62769-3 is technically identical to FDI-2023.

IEC 62769-4, *Field Device Integration (FDI) –Part 4: FDI Packages*

NOTE IEC 62769-4 is technical identically to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE IEC 62769-5 is technical identically to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE IEC 62769-6 is technical identically to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE IEC 62769-7 is technical identically to FDI-2027.

¹ FOUNDATION™ Fieldbus is the trade name of the non-profit consortium Fieldbus Foundation. This information is given for the convenience of users of this technical report and does not constitute an endorsement by IEC of the trademark holder or any of its products. Compliance does not require use of the trade name. Use of the trade name requires permission of the trade name holder.

IEC 62769-101-1, *Field Device Integration (FDI) – Part 101-1: Profiles – Foundation Fieldbus H1*

3 Terms, definitions, abbreviated terms and acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 61784-1, IEC 61784-2, IEC 61804, IEC 62541-100, IEC 62769-2, IEC 62769-3, IEC 62769-4, IEC 62769-5, IEC 62769-6, IEC 62769-7 and IEC 62769-101-1 apply.

3.2 Abbreviated terms and acronyms

For the purposes of this document, the following abbreviations apply:

CFF	Common File format
CP	communication profile (see IEC 61784-1 or IEC 61784-2)
CPF	communication profile family (see IEC 61784-1 or IEC 61784-2)
EDD	Electronic Device Description (see IEC 61804 series)
FB	function block
IM	Information Model
SMIB	system management information base
VFD	virtual field device

4 Conventions

4.1 EDDL syntax

This part of IEC 62769 specifies content for the EDD component that is part of FDI Communication Packages. EDDL syntax uses the font `Courier New`. EDDL syntax is used for method signature, variable, data structure and component declarations.

4.2 XML syntax

XML syntax examples use the font `Courier New`. The XML syntax is used to describe XML document schema.

EXAMPLE: `<xsd:simpleType name="Example">`

5 Profile for CP 1/2 (FOUNDATION™ HSE)

5.1 General

This profile annex specifies the protocol specifics needed for FDI Packages describing communication servers, gateways and devices.

5.2 Catalog profile

5.2.1 Protocol support files

5.2.1.1 Capability file

Each CP 1/2 FDI Device Package shall contain a capability file. The capability file part is described in Table 1.